

## CLAIMS

1. An optoelectronic connector comprising a package, an optical port, an electrical port, an optoelectronic circuit positioned in the package and connected to the optical port and electrical port, the optoelectronic circuit comprising a bare control and emission detection integrated circuit chip, an internal wall of the package being provided with metallized connections, pads of the integrated circuit being connected directly to the metallized connections, wherein the connector comprises laser diodes on the integrated circuit chip, the laser diodes being formed in a predetermined arrangement from a gallium arsenide substrate and deposited on the integrated circuit chip by transfer from an intermediate support that maintains the predetermined arrangement, the connector defining a base unit link.

2. The connector according to claim 1, wherein the laser diodes are transferred on the integrated circuit with a space between the diodes equal to a space between optical fiber terminations in the optical port.

3. The connector according to claim 1, wherein the package is a MID package made by means of a method with metallizations in two passes.

4. The connector according to claim 1, wherein the package is a MID package connected to the integrated

circuit by BGA connections, wire bonding or anisotropic film technology.

5. The connector according to claim 1, wherein shielding of the package is of a MID shielding.

6. The connector according to claim 1 wherein the laser diodes are VCSEL diodes, of GaAs material.

7. The connector according to claim 1, wherein the optical port comprises an inclined mirror, inclined at about 45°.

8. The connector according to claim 1, wherein the optical port comprises a part for positioning optical fiber terminations, this part abutting a cant of the integrated circuit.

9. The connector according to claim 1, wherein the optical port comprises a limited access with two optical channels and in that the electrical port comprises contacts for electrical signals and contacts for a ground signal.

10. The connector according to claim 1, wherein the package is a module and comprises means to be stacked on another package.

11. The connector according to claim 1, wherein pads of the laser diodes are connected by connection wires directly to pads of the integrated circuit.

12. The connector according to claim 1, wherein the optoelectronic circuit comprises means to carry out a conversion of the signals available at the optical port into signals available at the electrical port and/or vice versa.